AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-48 (Canceled).

49. (Previously Presented) An integrated method comprising: providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment being a treatment other than a thermal treatment; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability.

50. (Currently Amended) An integrated method comprising: providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment being a treatment other than a thermal treatment; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability The integrated method of elaim 49, wherein applying a first treatment comprises subjecting the low dielectric material to a treatment selected from a group consisting of hydrogen-based plasma, electron beam, ultraviolet radiation, and microwave hydrogen plasma.

51. (Currently Amended) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment being a treatment other than a thermal treatment; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability. The integrated method of elaim 49, wherein applying a second treatment comprises subjecting the low dielectric material after

the first treatment to a treatment selected from a group consisting of hydrogen-based plasma, electron beam, ultraviolet radiation, and carbon-based plasma, microwave hydrogen plasma.

- 52. (Previously Presented) An integrated method comprising:

 providing a low dielectric material;

 applying a first treatment altering a first property of the low dielectric material; and

 applying a second treatment altering a second property of the treated low dielectric material

 and producing a lower dielectric material with better mechanical stability, the second treatment being

 a treatment other than a thermal treatment.
- 53. (Currently Amended) An integrated method comprising:

 providing a low dielectric material;

 applying a first treatment altering a first property of the low dielectric material; and

 applying a second treatment altering a second property of the treated low dielectric material

 and producing a lower dielectric material with better mechanical stability, the second treatment being

 a treatment other than a thermal treatment The integrated method of claim 52, wherein applying a

 first treatment comprises subjecting the low dielectric material to a treatment selected from a group

 consisting of hydrogen-based plasma, electron beam, high temperature, ultraviolet radiation, and

 microwave hydrogen plasma.
- providing a low dielectric material;
 applying a first treatment altering a first property of the low dielectric material; and
 applying a second treatment altering a second property of the treated low dielectric material
 and producing a lower dielectric material with better mechanical stability, the second treatment being
 a treatment other than a thermal treatment The integrated method of claim 52, wherein applying a
 second treatment comprises subjecting the low dielectric material after the first treatment to a
 treatment selected from a group consisting of hydrogen-based plasma, electron beam, ultraviolet
 radiation, and carbon-based plasma, microwave hydrogen plasma.

(Currently Amended) An integrated method comprising:

54.

55. (Previously Presented) An integrated method comprising: providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with hydrogen-based plasma; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability.

56. (Currently Amended) <u>An integrated method comprising:</u> providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with hydrogen-based plasma; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability The integrated method of elaim 55, wherein applying the second treatment comprises a treatment selected from a group consisting of treating the low dielectric material with microwave hydrogen plasma and ultraviolet radiation.

- 57. (Cancelled) The integrated method of claim 55, wherein applying the second treatment comprises treating the low dielectric material with ultraviolet radiation.
 - 58. (Previously Presented) An integrated method comprising: providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with ultraviolet radiation; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability.

59. (Currently Amended) <u>An integrated method comprising:</u> providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with ultraviolet radiation; and

and producing a lower dielectric material with better mechanical stability The integrated method of elaim 58, wherein applying the second treatment comprises a treatment selected from a group consisting of treating the low dielectric material with carbon-based plasma and a hydrogen plasma.

- 60. (Cancelled) The integrated method of claim 58, wherein applying the second treatment comprises treating the low dielectric material with hydrogen plasma.
 - 61. (Previously Presented) An integrated method comprising: providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with microwave hydrogen plasma; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability.

- 62. (Previously Presented) The integrated method of claim 61, wherein applying the second treatment comprises treating the low dielectric material with carbon-based plasma.
- 63. (Previously Presented) The integrated method of claim 61, wherein applying the second treatment comprises treating the low dielectric material with hydrogen plasma.
 - 64. (Previously Presented) An integrated method comprising:
 providing a low dielectric material;
 applying a first treatment altering a first property of the low dielectric material;

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability; and

wherein one of the first and second treatment comprises treating the low dielectric material with a plasma.

65. (Previously Presented) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material;

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability; and

wherein one of the first and second treatment comprises treating the low dielectric material with ultraviolet radiation.

66. (Previously Presented) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material;

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability; and

wherein one of the first and second treatment comprises treating the low dielectric material with an electron beam.

67. (Previously Presented) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with high temperature; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability, the second treatment treating the low dielectric material with a plasma.